



Reliability Test Program of Diode

January 2011 /Rev. 3

NO	Test Item	Test Condition	Duration	Reference Standard
1	SOLDERABILITY	230°C ~ 260°C	5 SEC, 1 TIME	MIL-STD-750B, METHOD 2062.3
2	LEAD TENSION	2KG IN LEAD DIRECTION	10 SEC	MIL-STD-750B, METHOD 2036.3
3	LEAD FATIGUE	90° BEND WITH 0.5KG WEIGHT, ATTACHED TO LEAD	3 TIMES	MIL-STD-750B, METHOD 2036.3
4	LEAD TORQUE	1.45+/-0.145KG-MM	1 TIME	MIL-STD-750B, METHOD 2036.3
5	OPERATING LIFE	RATED VOLTAGE & CURRENT@25°C	72/168/1000HRS	MIL-STD-750B, METHOD 1027.1
6	HIGH TEMPERATURE REVERSE BIAS	80% RATED VOLTAGE@125°C	72/168/1000HRS	MIL-STD-750B, METHOD 1039
7	HIGH TEMPERATURE STORAGE LIFE	@125°C	72/168/1000HRS	MIL-STD-750B, METHOD 1031.4
8	MOISTURE RESISTANCE	85°C/85%RH	72/168/1000HRS	MIL-STD-750B, METHOD 1021.1
9	PRESSURE COOK	121°C/15PSIG	8/48/144HRS	MIL-S-19500, APPENDIX C
10	THERMAL SHOCK	-40°C/5MIN ~ 150°C/5MIN 25°C/10SEC FOR TRANSFER	8/50/100CYCLES	MIL-STD-750B, METHOD 1056.1
11	TEMPERATURE CYCLING	-10°C/30MIN ~ 100°C/30MIN 25°C/10MIN FOR TRANSFER	8/50/100CYCLES	MIL-STD-750B, METHOD 1051.2
12	SOLDERING HEAT	260°C +/- 5°C	10SEC 1TIME	MIL-STD-750B, METHOD 2031.1
13	SALT SPRAY	5% SALT SOLUTION UNDER 35°C AIR/47°C CHAMBER	48HRS	MIL-STD-750B, METHOD 1046.2